

**MDTE Series**

Wire Wound Molded SMD Power Inductors

Size 6060

**FEATURES**

- Soft saturation
- High current, low DCR, high efficiency
- Very low acoustic noise and very low leakage flux noise
- High reliability
- 100% Lead(Pb)-Free and RoHS compliant
- Operating temperature -55~+125 °C (Including self - temperature rise)
- Quantity: 750pcs

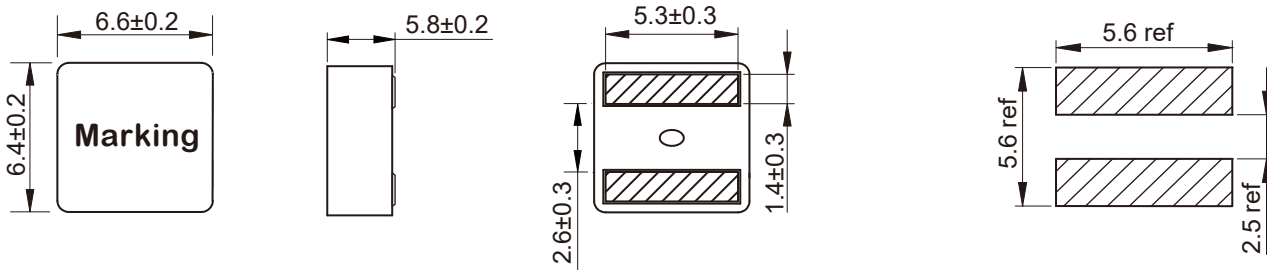


**APPLICATION**

- Note PC power system, incl. IMVP-6
- DC/DC converter

Dimensions: [mm]

Land Pattern: [mm]



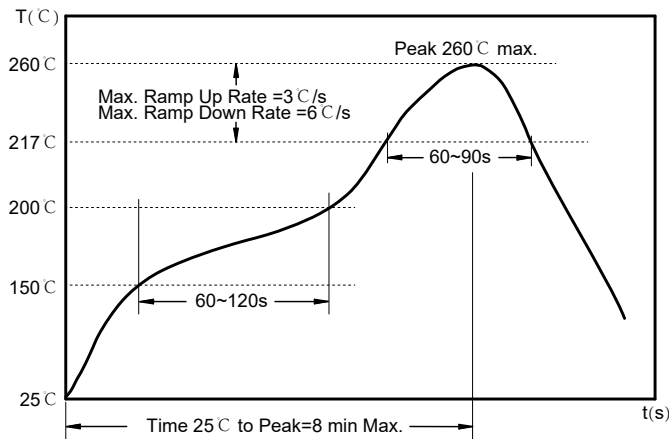
Electrical Properties:

Part No	Inductance @ 100KHz/0.1V (μH)	Tolerance	Saturation Current Typ. (A)	Saturation Current Max. (A)	Temperature Rise Current Typ. (A)	DC Resistance Max. (mΩ)
MDTE6060-1R0M	1.0	±20%	24.0	19.0	21.0	4.40
MDTE6060-1R5M	1.5	±20%	20.0	15.0	17.5	6.10
MDTE6060-2R2M	2.2	±20%	16.5	12.5	14.0	8.10
MDTE6060-3R3M	3.3	±20%	13.0	11.0	12.0	12.3
MDTE6060-4R7M	4.7	±20%	10.5	9.3	11.0	14.4
MDTE6060-5R6M	5.6	±20%	9.9	8.7	10.0	15.9
MDTE6060-6R8M	6.8	±20%	9.2	8.1	9.0	20.8
MDTE6060-8R2M	8.2	±20%	8.4	8.0	8.0	26.4
MDTE6060-100M	10	±20%	7.6	6.8	7.0	29.82
MDTE6060-150M	15	±20%	5.8	5.0	6.0	43.75
MDTE6060-220M	22	±20%	5.6	4.8	5.0	60.63

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is ΔT=40°C

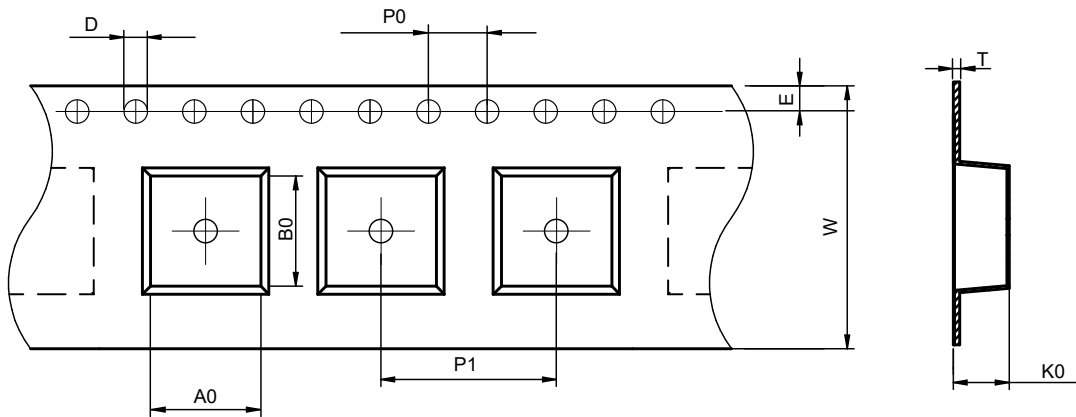
### Soldering Reflow:



Preheat condition: 150 ~200°C / 60~120 sec.  
 Allowed time above 217°C: 60~90 sec.  
 Max temperature: 260°C.  
 Max time at max temperature: 10 sec.  
 Allowed Reflow time: 2x max.

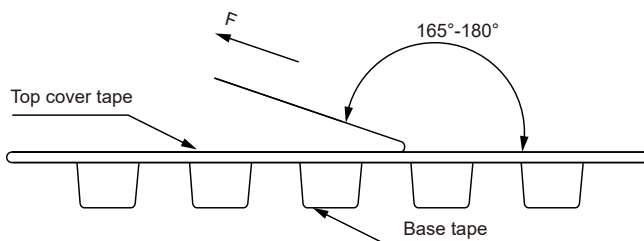
### Packaging Information:

#### Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTE6060	7.0±0.1	6.8±0.1	1.5±0.1	4.0±0.1	12.0±0.1	16.0±0.3	6.3±0.1	1.75±0.1	0.35±0.05

#### Peel force of top cover tape:

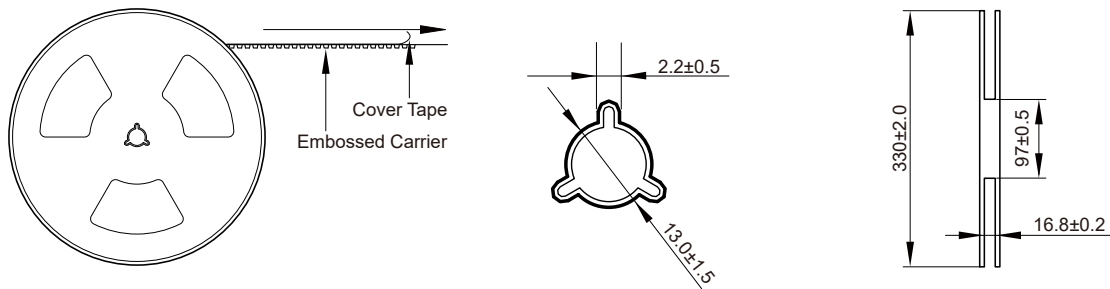


The peel force of top cover tape shall be between 0.1 to 1.3 N

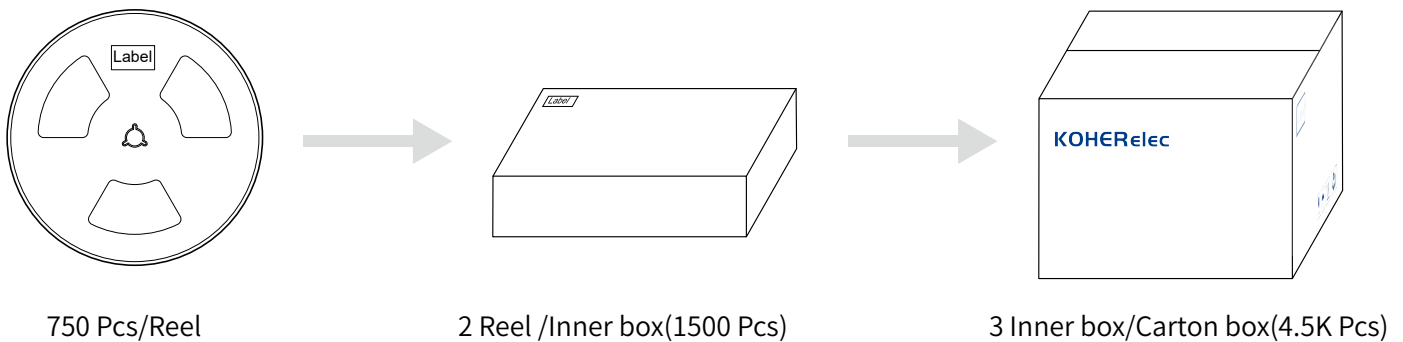
#### Product Marking:

Marking	Printing (Inductance)
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Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions :

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.